

# The DUET Series

Dual Interface Milling & Embedding

## DUET WirePRO™

Dual Interface Milling & Embedding

- Direct Solder Process
- Cavity Milling
- Module Embedding
- ATR & ATS Testing

**Output:** 2500-3000 CPH

**Voltage:** 380VAC 50/60 Hz

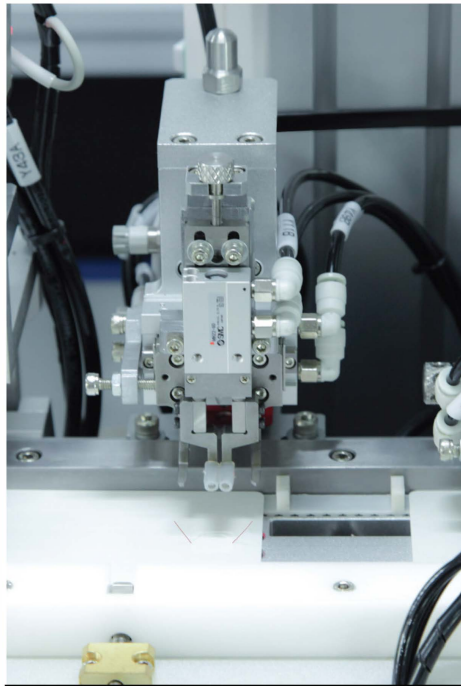
**Power:** 11kW

**Compressed Air:** 6kg/cm<sup>2</sup> 220L/min

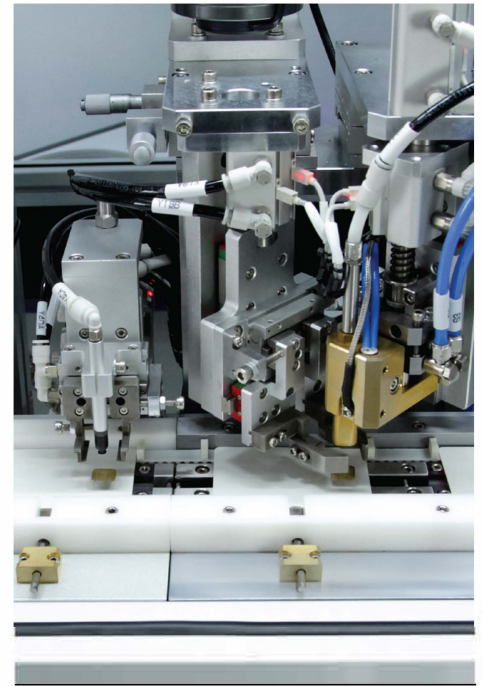
**Dims:** [L]4900mm [W]1050mm

[H]1950mm

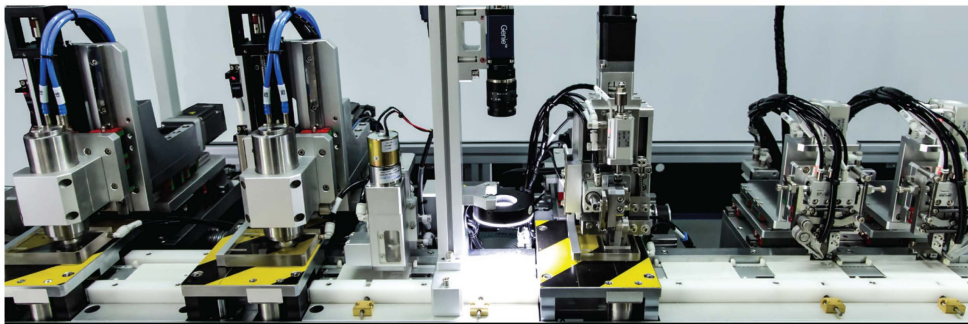
**Multimedia:** [Video Link](#)



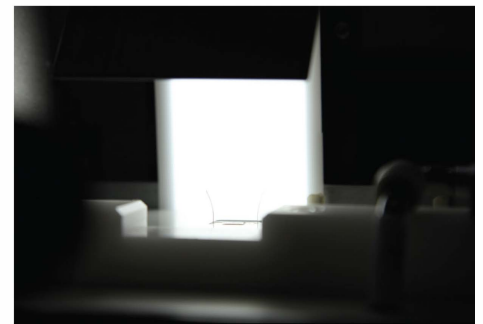
**DUET WirePRO**  
Antenna Preparation



**DUET WirePRO**  
Module Embedding



**DUET WirePRO**  
Stations



**DUET WirePRO**  
HD Vision Inspection

Developed by Cardmatix, the patented Direct-Solder Process drives the production of over 500 million dual interface banking cards a year. No other process offers the RF performance, longevity, or durability of a solder connection. A direct-solder connection does not impair RF performance, and will not decay or change with time.

**The Direct-Solder Method** is the process of soldering a copper wire antenna embedded within the card body directly to wire antenna pads on the back of the dual interface module.

**Consumables:** There are no hidden costs or complicated logistics associated with sourcing proprietary glues, inlays, or special module designs.

**Removable Magazines:** Attach or detach magazines for easy loading and unloading of cards.

**Cavity Milling:** The WirePRO is equipped with three cavity milling stations to expose the antenna and then form the final module cavity.

**Antenna Preparation:** Using vision controlled robotics, the antenna leads are located, QC checked, and pulled from the cavity.

**Direct-Solder:** Antenna leads are soldered to the dual interface module using thermal compression method.

**Wire Dressing:** The antenna leads are folded under the module.

**Module Embedding** - is the process of embedding the module into the card body with the hot-melt glue tape lamination process with three hot-pressers and one cold presser.

**Glue Tape:** The WirePRO uses traditional hot-melt glue tape commonly available on the market.

**ATS:** Contactless interface functioning is tested first after antenna connection, and again after module embedding.

**ATR:** Contact interface functioning is tested after embedding.